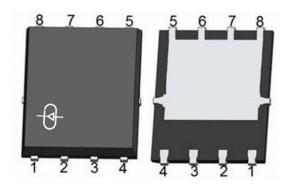


100A, 30V N-CHANNEL SUPER TRENCH POWER MOSFET

DESCRIPTION:



The ALP100N03S is an 100A, 30V N-Channel Super Trench Power MOSFET and it has fast a very low on-resistance R_{DS(on)}

FEATURES:

- V_{(BR)DSS} = 30V, I_D = 100A
- $Arr R_{DS(ON)MAX} = 2.5 mΩ$ @V_{GS} = 10V, I_D = 100A.
- $Arr R_{DS(ON)MAX} = 3.5 mΩ$ @V_{GS} = 4.5V, I_D = 100A.
- Very low on-resistance R_{DS(on)}.
- Excellent package for heat dissipation.
- Lead-free parts meet RoHS requirements
- Suffix "-H" indicated Halogen Free part, ex. ALP100N03S-H

APPLICATIONS:

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply.

MECHANICAL CHARACTERISTICS

Case: Molded plastic, DFN5X6-8L

Mounting Position: Any.



beyond boundaries...

ALP100N03S DFN5X6-8L

MAXIMUM RATINGS

MAXIMUM RATINGS @ T_A = 25 °C unless otherwise specified					
PARAMETER	SYMBOL	RATINGS	UNIT		
Drain-Source Voltage	V_{DS}	30	V		
Gate-Source Voltage	V_{GS}	±20	V		
Continuous Drain Current					
T _C =25°C	I _D	100	Α		
T _C =100°C		70.7			
Pulsed Drain Current	I _{DM}	300	А		
Power Dissipation	P_{D}	65	W		
Thermal Resistance Junction to Case	$R_{ heta$ JC	2.3	°C/W		
Operating Junction Temperature	TJ	+150	°C		
Storage Temperature Range	T _{STG}	-55 to +150	°C		



ELECTRICAL CHARACTERISTICS @ TA = 25 °C unless otherwise specified

PARAMETER	CONDITIONS	SYMBOL	MIN	TYP.	MAX	UNIT
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250 μA	V _{(BR)DSS}	30			V
Zero gate voltage drain current	V _{DS} =30V, V _{GS} =0V	I _{DSS}			1.0	μΑ
Gate-body leakage current	V _{GS} = ±20V, V _{DS} = 0V	I _{GSS}			±100	nA
ON CHARACTERISTICS						
Gate-Threshold Voltage	$V_{DS} = V_{GS}$, $I_{D} = 250 \mu A$	$V_{GS(th)}$	1.2		2.5	V
Drain-to-Source On-Resistance	$V_{GS} = 10V, I_D = 20A$	D			2.5	
(Note 1)	$V_{GS} = 4.5V, I_D = 10A$	R _{DS(ON)}			3.5	mΩ
Forward transconductance (Note 1)	V _{DS} =10V, I _D =20A	g _{FS}	32			S

DYNAMIC CHARACTERISTICS (Note 2)						
PARAMETER	CONDITIONS	SYMBOL	MIN	TYP.	MAX	UNIT
Input Capacitance	$V_{DS} = 15V$, $V_{GS} = 0V$, $F_{req} = 1.0$ MHz	C _{iss}		5000		pF
Output Capacitance	$V_{DS} = 15V$, $V_{GS} = 0V$, $F_{req} = 1.0$ MHz	Coss		1135		pF
Reserve Transfer Capacitance	$V_{DS} = 15V, V_{GS} = 0V, F_{req} = 1.0 \text{ MHz}$	C_{rss}		563		pF

SWITCHING CHARACTERISTICS						
PARAMETER	CONDITIONS SYMBOL MIN		MIN	TYP.	MAX	UNIT
Total Gate Charge	$V_{DS} = 15V$, $V_{GS} = 10V$, $I_D = 20A$	Qg		38		nC
Gate to Source Charge	$V_{DS} = 15V$, $V_{GS} = 10V$, $I_{D} = 20A$	Q_{gs}		9		nC
Gate to Drain Charge	$V_{DS} = 15V$, $V_{GS} = 10V$, $I_{D} = 20A$	Q_{gd}				nC
Turn-On Delay Time	$V_{DD} = 15V, V_{GS} = 10V,$ $R_{L} = 15\Omega, R_{GEN} = 2.5\Omega$	t _{d(on)}		26		nS
Turn-On Rise time	e time $\begin{aligned} V_{DD} &= 15 V, V_{GS} = 10 V, \\ R_L &= 15 \Omega, R_{GEN} = 2.5 \Omega \end{aligned}$			24		nS
Turn-Off Delay Time	$V_{DD} = 15V, V_{GS} = 10V,$ $R_{L} = 15\Omega, R_{GEN} = 2.5\Omega$	t _{d(off)}		91		nS
Turn-Off Fall time	$V_{DD} = 15V, V_{GS} = 10V,$ $R_{L} = 15\Omega, R_{GEN} = 2.5\Omega$	t _f 39		39		nS

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS						
PARAMETER CONDITIONS		SYMBOL	MIN	TYP.	MAX	UNIT
Diode forward Current (Note 1)		Is			100	Α
Diode forward Voltage $I_S = 10A$, $V_{GS} = 0V$		V_{DS}			1.2	V
Reverse recovery time $T_J = 25$ °C, $I_F = 20$ A, $di/dt = 100$ A/ μ s (Note 1)		t _{rr}		42		nS
Reverse recovery charge	$T_J = 25$ °C, $I_F = 20A$, $di/dt = 100A/\mu s$ (Note 1)	Q _{rr}		39		nC

Note:

- 1. Pulse test (pulse width \leq 300 μ s, Duty cycle \leq 2%.
- 2. Guaranteed by design, not subject to production testing.



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TYPICAL DEVICE RATING AND CHARACTERISTICS CURVES (TA = 25 °C unless otherwise noted)

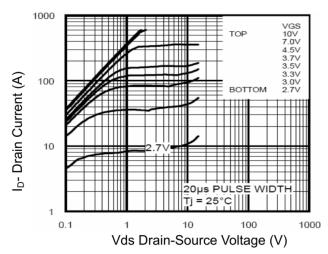


Fig.1 OUTPUT CHARACTERISTICS

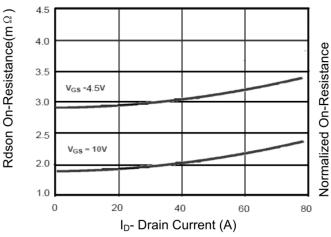
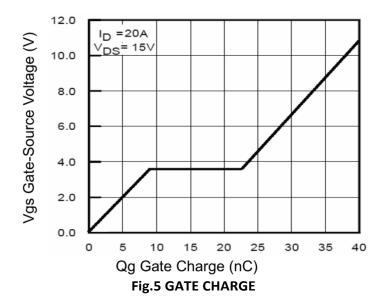


Fig.3 R_{DS(on)} - DRAIN CURRENT



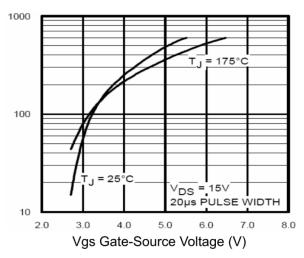


Fig.2 TRANSFER CHARACTERISTICS

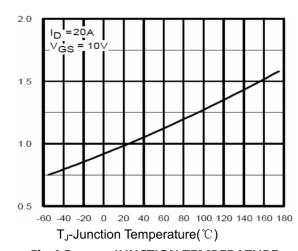


Fig.4 R_{DS(on)} – JUNCTION TEMPERATURE

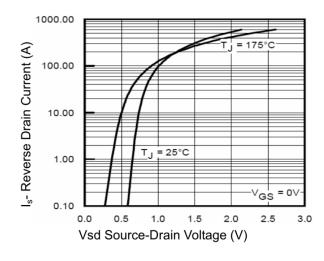


Fig.6 SOURCE – DRIAN DIODE FORWARD



100000

VGS = 0V, f = 1 MHZ

C_{iss} = C_{gs} + C_{gd}, C_{ds} SHORTED

C_{rss} = C_{gd}

C_{oss} = C_{ds} + C_{gd}

Vds Drain-Source Voltage (V) Fig.7 CAPACITANCE vs V_{DS}

10

100

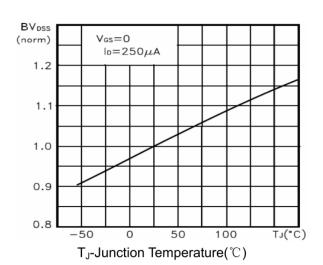


Fig.9 BV_{DSS} vs JUNCTION TEMPERATURE

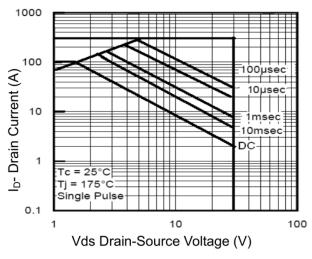


Fig.8 SAFE OPERATION AREA

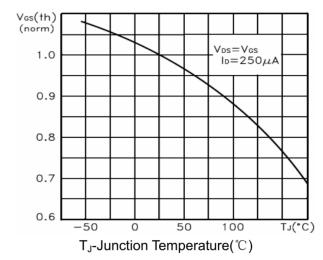


Fig. 10 V_{GS(th)} vs JUNCTION TEMPERATURE

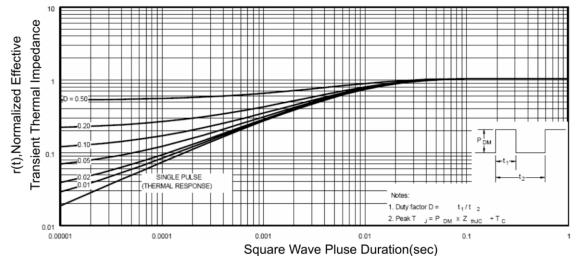


Fig.11 NORMALIZED MAXIMUM TRANSIENT THERMAL IMPEDANCE





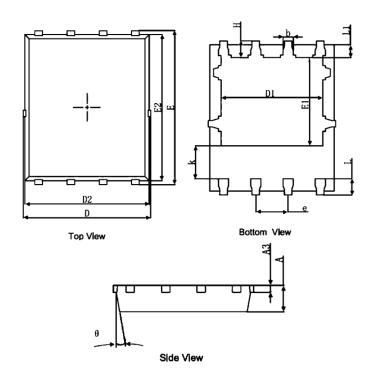
PINNING INFORMATION

PIN	SIMPLIFIED OUTLINE	CIRCUIT DIAGRAM
Pin1 Source Pin2 Source Pin3 Source Pin4 Gate Pin5 Drain Pin6 Drain Pin7 Drain Pin8 Drain	1 2 3 4	G S



PACKAGE INFORMATION

DFN5X6-8L



OUTLINE DIMENSIONS					
	MILLIMETERS		INCH	IES	
SYMBOL	MIN	MAX	MIN	MAX	
А	0.900	1.000	0.035	0.039	
А3	0.254REF.		0.010	REF.	
b	0.350	0.450	0.014	0.018	
D	4.944	5.096	0.195	0.201	
D1	3.910	4.110	0.154	0.162	
D2	4.824	4.976	0.190	0.196	
E	5.974	6.126	0.235	0.241	
E1	3.375	3.575	0.133	0.141	
E2	5.674	5.826	0.223	0.229	
e	1.27	OTYP.	0.050	TYP.	
k	1.190	1.390	0.047	0.055	
L	0.559	0.711	0.022	0.028	
L1	0.424	0.576	0.017	0.023	
Н	0.574	0.726	0.023	0.029	
θ	8°	12°	8°	12°	

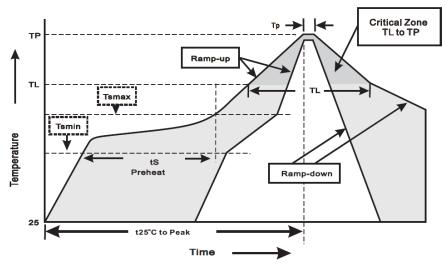


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SOLDERING PARAMETERS

SUGGESTED THERMAL PROFILES FOR SOLDERING PROCESSES

- 1. Storage environment: Temperature=5 °C~40 °C Humidity=55% ±25%
- 2. Reflow soldering of surface-mount devices



3. Reflow soldering

PROFILE FEATURE	SOLDERING CONDITION
Average ramp-up rate (T _L to T _P)	<3 °C/sec
Preheat	
- Temperature Min (T _{smin})	150 °C
- Temperature Max (T _{smax})	200 °C
- Time (min to max) (t _s)	60 ~ 120 sec
T _{smax} to T _L	
- Ramp-upRate	<3 °C/sec
Time maintained above:	
- Temperature (T _L)	217 °C
- Time(tL)	60 ~ 260 sec
Peak Temperature (T _P)	255 °C-0/+5 °C
Time within 5 °C of actual Peak	10 ~ 30 sec
Temperature(tP)	
Ramp-down Rate	<6 °C/sec
Time 25 °C to Peak Temperature	<6 minutes



CUSTOMER NOTE:

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- 1. ALPINESEMI™ Semiconductor Devices are RoHS compliant and hence customers are requested to dispose as per the prevailing Environmental Legislation put forth in their specific country.
- 2. In Europe, please dispose as per EU Directive 2002/96/EC on Waste Electrical and Electronic Equipment (WEEE).



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